Final Product Change Notification

202101023F01 : WLAN8101H/C 2nd Source Bumping/Assembly/Diffusion (H Type Only) Release + PQ Increase

Note: This notice is NXP Company Proprietary.

Issue Date: Jun 20, 2021 **Effective date:Sep 18, 2021**

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Management summary

WLAN8101H/C 2nd source release: bumping/assembly (CB-KF/TFME) and wafer fab ICN8 (for H type only).
PQ increase at NXP ATKH.
This PCN was announced and aligned with customers via APCN 202101023A as fast approvals needed to guarantee supply.

Change Category

[ ]Wafer Fab Process	[ ]Assembly Process	[X]Product Marking	[ ]Test Process	[ ]Design
[ ]Wafer Fab Materials	[ ]Assembly Materials	[ ]Mechanical Specification	[ ]Test Equipment	[ ]Errata
[X]Wafer Fab Location	[X]Assembly Location	[X]Packing/Shipping/Labeling	[ ]Test Location	[ ]Electrical spec./Test coverage
[ ]Firmware	[ ]Other			

PCN Overview

Description

WLAN8101H/C 2nd source release: bumping/assembly (CB-KF/TFME) and wafer fab ICN8 (for H type only).
PQ increase at NXP ATKH

Reason

2nd source: to maximize flexibility in supply.
PQ increase: to improve FT efficiency.

Identification of Affected Products

Top Side Marking
Line C on the product marking will indicate the different bumping side.
t=ASE
h=CB-KF

Product Availability

Sample Information
Samples are available from Apr 23, 2021
Production
Planned first shipment Jun 21, 2021

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality
Data Sheet Revision
No impact to existing datasheet
Disposition of Old Products
NA

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jul 20, 2021.

Related Notification

Notification	Issue Date	Effective Date	Title
202101023A	Jan 27, 2021		WLAN8101H/C 2nd Source Bumping/Assembly/Diffusion (H Type Only) Release + PQ Increase

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.
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Changed Orderable Part#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
WLAN8101CMP	934072084528	WLAN8101C	QFN Module	H(W)FCFLGA38SIP	SOT2022-1	RFS	No	BL21
WLAN8101HMP	934072085528	WLAN8101H	QFN Module	H(W)FCFLGA38SIP	SOT2022-1	RFS	No	BL21